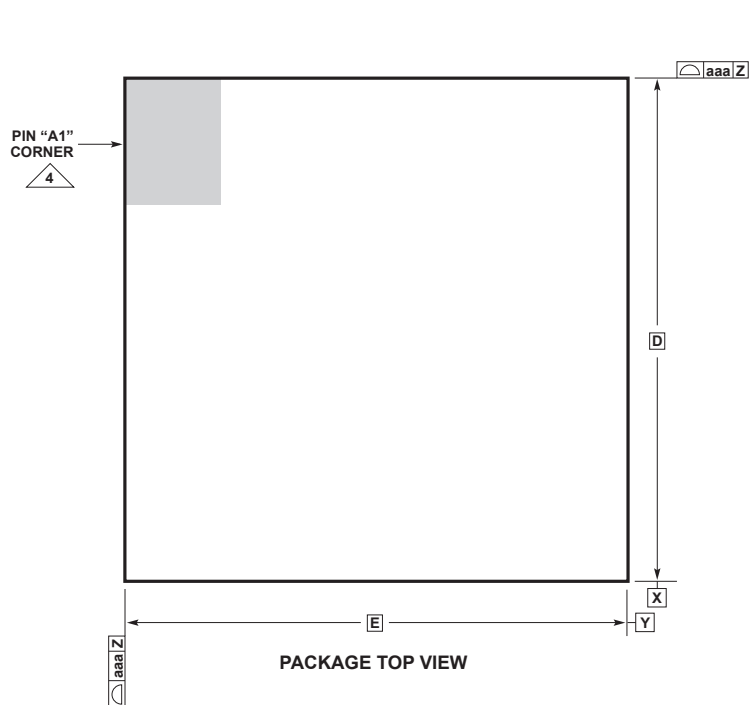
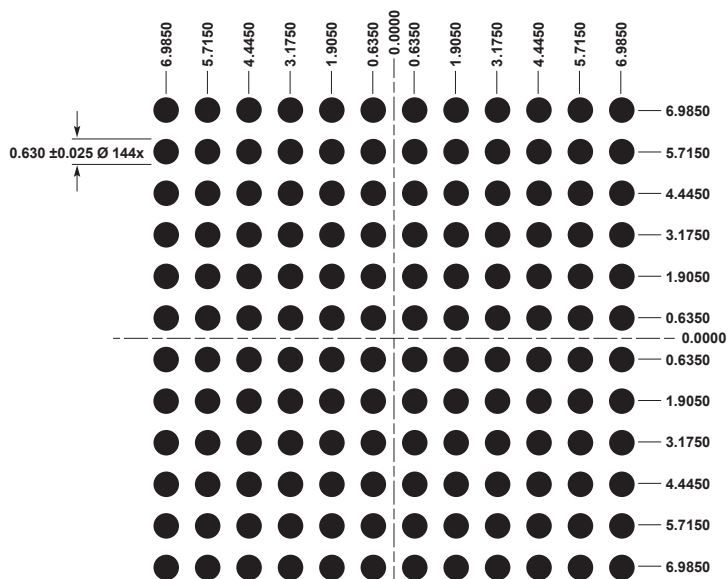


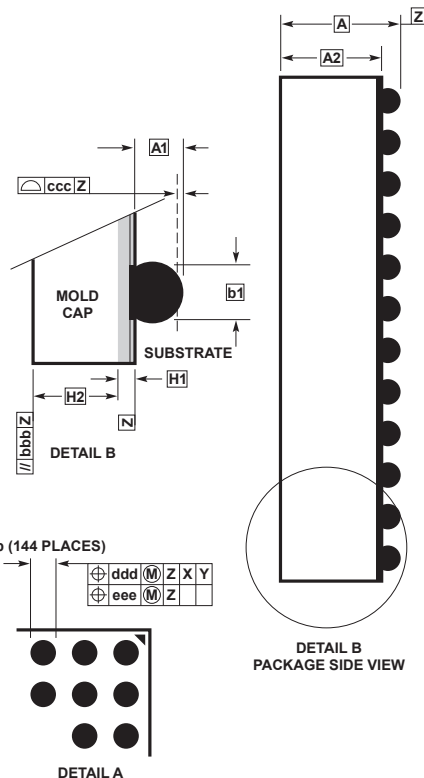
BGA Package
144-Lead (16mm × 16mm × 5.01mm)
 (Reference DWG # 05-08-1551)



PACKAGE TOP VIEW



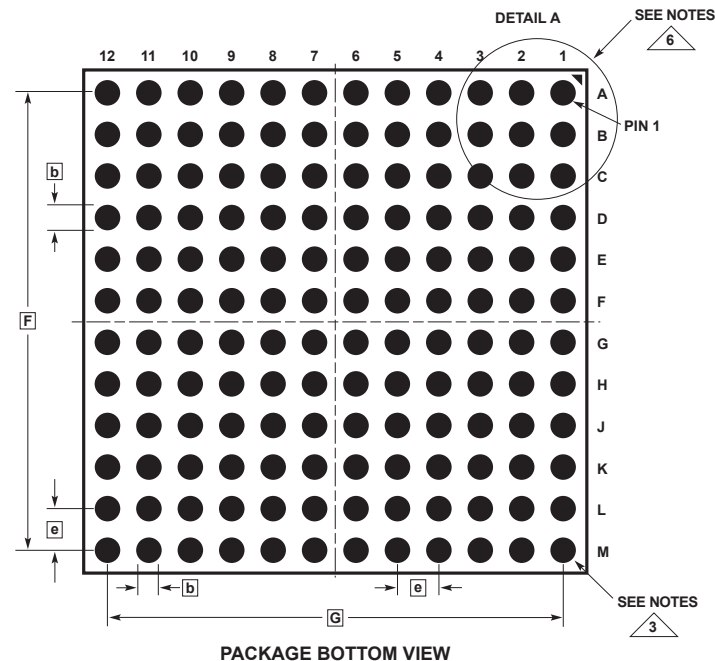
SUGGESTED PCB LAYOUT
TOP VIEW



DETAIL B
PACKAGE SIDE VIEW

DETAIL A

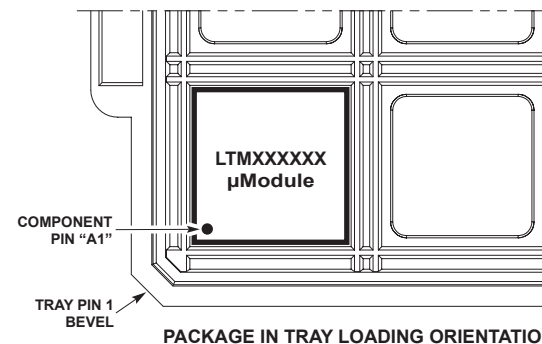
DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.81	5.01	5.21	
A1	0.50	0.60	0.70	
A2	4.31	4.41	4.51	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D	16.00			
E	16.00			
e	1.27			
F	13.97			
G	13.97			
H1	0.36	0.41	0.46	
H2	3.95	4.00	4.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 144				



PACKAGE BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μ Module PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION